

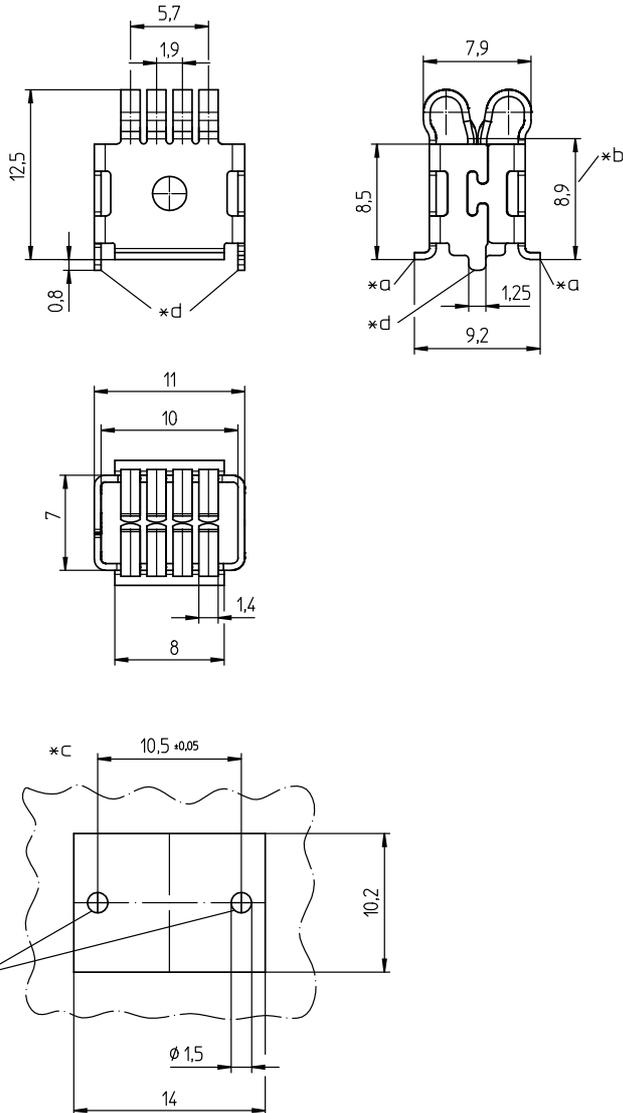
45 4580 04 MP T1,0

High-current contact elements



High-current contact bush with positioning pegs, for tab contacts 1.0 mm, for printed circuit boards or lead frames

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Environmental conditions

Temperature range -40 °C/+120 °C

Materials

Contact CuNiSi alloy, tin-plated

Mechanical data

Mating with tab contact 8.0 mm x 1.0 mm
applicable for reflow soldering on
printed circuit board
applicable for laser welding on
lead frame, e.g. Cu, tin-plated

Mating cycles ≤ 5
Insertion force 30 N ± 10 N¹
Withdrawal force 10 N ± 5 N¹

¹ measured with a polished steel pin, nominal dimensions 8.0 x 1.0 mm

Electrical data (at T_{amb} 20 °C)

Contact resistance < 0.5 mΩ
Rated current 75 A
(up to 200 A)¹

¹ depending on the connection to the printed circuit board/lead frame, installation situation and heat dissipation

- *a positioning peg
- *b supporting surface for reflow soldering or laser welding
- *c height contact point
- *d mounting space on printed circuit board or lead frame
- *e bore hole for positioning peg

45

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Designation	Pole Number	PU (Pieces)	MDQ (Pieces)
4580 04 MP T1,0 V11VP9	1	5000	10000
4580 04 MP T1,0 V11VP12	1	300	2400

Packaging:

4580 04 MP T1,0 V11VP9 in a cardboard box

4580 04 MP T1,0 V11VP12 on reel